

S B U -D T

FXLP34

Description

The FXLP34 is a single translator with two separate supply voltages: V_{CC1} for input translation voltages and V_{CC} for output translation voltages. The FXLP34 is part of **onsemi**'s Ultra Low Power (ULP) series of products. This device operates with VCC values from 1.0 V to 3.6 V, and is intended for use in portable applications that require ultra low power consumption.

The internal circuit is composed of a minimum of buffer stages, to enable ultra low dynamic power.

The FXLP34 is uniquely designed for optimized power and speed, and is fabricated with an advanced CMOS technology to achieve high-speed operation while maintaining low CMOS power dissipation.

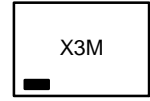
Features

- 1.0 V to 3.6 V V_{CC} Supply Voltage
- Converts Any Voltage (1.0 V to 3.6 V) to (1.0 V to 3.6 V)
- 4.6V Tolerant Inputs and Outputs
- t_{PD} :
 - ◆ 4 ns Typical for 3.0 V to 3.6 V V_{CC}
- Power-Off High Impedance Inputs and Outputs
- Static Drive (I_{OH}/I_{OL}):
 - ◆ ± 2.6 mA at 3.00 V V_{CC}
- Uses Proprietary Quiet Series Noise / EMI Reduction Circuitry
- Ultra-Small MicroPak™ Leadless Packages
- Ultra-Low Dynamic Power
- These are Pb-Free Devices

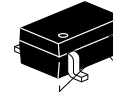
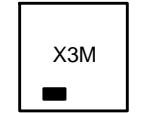


SIP6 1.45X1.0
CASE 127EB

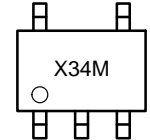
MARKING DIAGRAM



UDFN6
1.0X1.0, 0.35P
CASE 517DP



SC-88A (SC-70
5 Lead), 1.25x2
CASE 419AC-01



X3, X34 = Device Code
M = Assembly Operation Month

ORDERING INFORMATION

See detailed ordering and shipping information on page 9 of this data sheet.

FXLP34

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter		Min	Max	Unit
V _{CC} , V _{CC1}	Supply Voltage		-0.5	+4.6	V
V _{IN}	DC Input Voltage		-0.5	+4.6	V
V _{OUT}	DC Output Voltage	HIGH or LOW State (Note 1)	-0.5	V _{CC} + 0.5 V	V
		V _{CC} = 0 V	-0.5	+4.6	
I _{IK}	DC Input Diode Current	V _{IN} < 0	-	-50	mA
I _{OK}	DC Output Diode Current	V _{OUT} < 0 V	-	-50	mA
		V _{OUT} > V _{CC}	-	+50	
I _{OH} /I _{OL}	DC Output Source/Sink Current		-	±50	mA
I _{CC} or I _{GND}	DC V _{CC} or Ground Current per Supply Pin		-	±100	mA
T _{STG}	Storage Temperature Range		-65	150	°C
P _D	Power Dissipation at +85°C	SC70-6	-	180	mW
		MicroPak™ -6	-	130	
		MicroPak2™ -6	-	120	
ESD	Human Body Model, JEDEC:JESD22-A114		-	4000	V
	Charge Device Model, JEDEC:JESD22-C101		-	2000	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. I_O Absolute Maximum Rating must be observed.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC} , V _{CC1}	Supply Voltage		1.0	3.6	V

FXLP34

ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Condition	V _{CC} (V)	V _{CC1} (V)	T _A = +25°C		T _A = -40 to 85°C		Unit
					Min	Max	Min	Max	
V _{IH}	HIGH Level Input (V _{CC1})		1.0 to 3.6	1.0	0.65 x V _{CC1}	-	0.65 x V _{CC1}	-	V
				1.10 ≤ V _{CC1} ≤ 1.30	0.65 x V _{CC1}	-	0.65 x V _{CC1}	-	
				1.40 ≤ V _{CC1} ≤ 1.60	0.65 x V _{CC1}	-	0.65 x V _{CC1}	-	
				1.65 ≤ V _{CC1} ≤ 1.95	0.65 x V _{CC1}	-	0.65 x V _{CC1}	-	
				2.30 ≤ V _{CC1} ≤ 2.70	1.6	-	1.6	-	
				3.00 ≤ V _{CC1} ≤ 3.60	2.1	-	2.1	-	
V _{IL}	LOW Level Input (V _{CC1})		1.0 to 3.6	1.0	-	0.35 x V _{CC1}	-	0.35 x V _{CC1}	V
				1.10 ≤ V _{CC1} ≤ 1.30	-	0.35 x V _{CC1}	-	0.35 x V _{CC1}	
				1.40 ≤ V _{CC1} ≤ 1.60	-	0.35 x V _{CC1}	-	0.35 x V _{CC1}	
				1.65 ≤ V _{CC1} ≤ 1.95	-	0.35 x V _{CC1}	-	0.35 x V _{CC1}	
				2.30 ≤ V _{CC1} ≤ 2.70	-	0.7	-	0.7	
				3.00 ≤ V _{CC1} ≤ 3.60	-	0.9	-	0.9	
V _{OH}	HIGH Level Output (V _{CC})	I _{OH} = -20 μA	1.0	1.0 to 3.6	V _{CC} - 0.1	-	V _{CC} - 0.1	-	V
			1.10 ≤ V _{CC1} ≤ 1.30		V _{CC} - 0.1	-	V _{CC} - 0.1	-	
			1.40 ≤ V _{CC1} ≤ 1.60		V _{CC} - 0.1	-	V _{CC} - 0.1	-	
			1.65 ≤ V _{CC1} ≤ 1.95		V _{CC} - 0.1	-	V _{CC} - 0.1	-	
			2.30 ≤ V _{CC1} ≤ 2.70		V _{CC} - 0.1	-	V _{CC} - 0.1	-	
			3.00 ≤ V _{CC1} ≤ 3.60		V _{CC} - 0.1	-	V _{CC} - 0.1	-	
		I _{OH} = -0.5 mA	1.10 ≤ V _{CC1} ≤ 1.30	1.0 to 3.6	0.75 x V _{CC}	-	0.70 x V _{CC}	-	
		I _{OH} = -1.0 mA	1.40 ≤ V _{CC1} ≤ 1.60		1.07	-	0.99	-	
		I _{OH} = -1.5 mA	1.65 ≤ V _{CC1} ≤ 1.95		1.24	-	1.22	-	
		I _{OH} = -2.1 mA	2.30 ≤ V _{CC1} ≤ 2.70		1.95	-	1.87	-	
		I _{OH} = -2.6 mA	3.00 ≤ V _{CC1} ≤ 3.60		2.61	-	2.55	-	
V _{OL}	LOW Level Output (V _{CC})	I _{OL} = 20 μA	1.0	1.0 to 3.6	-	0.1	-	0.1	V
			1.10 ≤ V _{CC1} ≤ 1.30		-	0.1	-	0.1	
			1.40 ≤ V _{CC1} ≤ 1.60		-	0.1	-	0.1	
			1.65 ≤ V _{CC1} ≤ 1.95		-	0.1	-	0.1	
			2.30 ≤ V _{CC1} ≤ 2.70		-	0.1	-	0.1	
		I _{OL} = 0.5 mA	1.10 ≤ V _{CC1} ≤ 1.30	1.0 to 3.6	-	0.30 x V _{CC}	-	0.30 x V _{CC}	
		I _{OL} = 1.0 mA	1.40 ≤ V _{CC1} ≤ 1.60		-	0.31	-	0.37	
		I _{OL} = 1.5 mA	1.65 ≤ V _{CC1} ≤ 1.95		-	0.31	-	0.35	
		I _{OL} = 2.1 mA	2.30 ≤ V _{CC1} ≤ 2.70		-	0.31	-	0.33	
		I _{OL} = 2.6 mA	3.00 ≤ V _{CC1} ≤ 3.60		-	0.31	-	0.33	
I _{IN}	Input Leakage Current	0 ≤ V _{IN} ≤ 3.60		1.0 to 3.6	-	±0.1	-	±1.0	μA
I _{OFF}	Power Off Leakage Current	0 ≤ (V _{IN} , V _O) ≤ 3.60	0	0	-	1.0	-	5.0	μA
I _{CC}									

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AC ELECTRICAL CHARACTERISTICS (continued)

Symbol	Parameter	Condition	V _{CC} (V)	T _A = +25°C			T _A = -40 to 85°C		Unit	Figure
				Min	Typ	Max	Min	Max		
t _{PHL} , t _{PLH}	Propagation Delay Output Translation V _{CC} (V) = 1.0	C _L = 15 pF, R _L = 1 MΩ	1.0	-	28.0	-	-	-	ns	Figure 3, Figure 4
			1.10 to 1.30	16.0	27.0	43.0	12.0	44.8		
			1.40 to 1.60	15.0	26.0	41.6	11.0	43.6		
			1.65 to 1.95	14.0	25.0	40.9	10.0	47.9		
			2.30 to 2.70	13.0	24.0	40.5	9.0	47.5		
			3.00 to 3.60	12.0	23.0	40.4	8.0	41.4		
t _{PHL} , t _{PLH}	Propagation Delay Output Translation V _{CC} (V) = 1.2	C _L = 15 pF, R _L = 1 MΩ	1.0	-	19.0	-	-	-	ns	Figure 3, Figure 4
			1.10 to 1.30	9.0	16.0	24.6	8.0	43.1		
			1.40 to 1.60	8.5	15.0	23.1	7.5	42.2		
			1.65 to 1.95	8.0	14.0	22.4	7.0	31.4		
			2.30 to 2.70	7.5	13.0	21.8	6.5	30.7		
			3.00 to 3.60	7.0	13.0	21.6	6.0	30.5		
t _{PHL} , t _{PLH}	Propagation Delay Output Translation V _{CC} (V) = 1.5	C _L = 15 pF, R _L = 1 MΩ	1.0	-	15.0	-	-	-	ns	Figure 3, Figure 4
			1.10 to 1.30	6.0	12.0	17.2	5.5	21.5		
			1.40 to 1.60	5.8	11.0	15.7	5.0	20.3		
			1.65 to 1.95	5.51						

FXLP34

AC ELECTRICAL CHARACTERISTICS (continued)

Symbol	Parameter	Condition	V _{CC} (V)	T _A = +25°C			T _A = -40 to 85°C		Unit	Figure
				Min	Typ	Max	Min	Max		
t _{PHL} t _{PLH}	Propagation Delay Output Transition V _{CC} V									

FXLP34

Translator Power-up Sequence Recommendations

To ensure that the system does not experience unnecessary I_{CC} current draw, bus contention, or oscillations during power-up; adhere to the following guidelines. This device is designed with the output pin(s) supplied by V_{CC} and the input pin(s) supplied by V_{CC1} . The first recommendation is to begin by powering up the input side of the device with V_{CC1} . The Input pin(s) should be ramped with or ahead of V_{CC1} or held LOW. This guards against bus contentions and oscillations as all inputs and the

input V_{CC1} are powered at the same time. The output V_{CC} can then be powered to the target voltage level to which the device will translate. The output pin(s) then translate to logic levels dictated by the output V_{CC} levels.

Upon completion of these steps, the device can be configured for the desired operation. Following these steps helps prevent possible damage to the translator device as well as other system components

AC Loadings and Waveforms

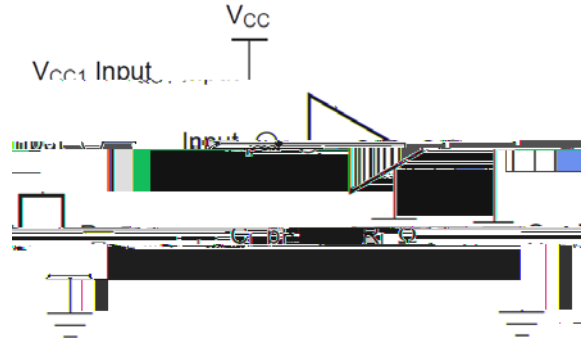


Figure 3. AC Test Circuit

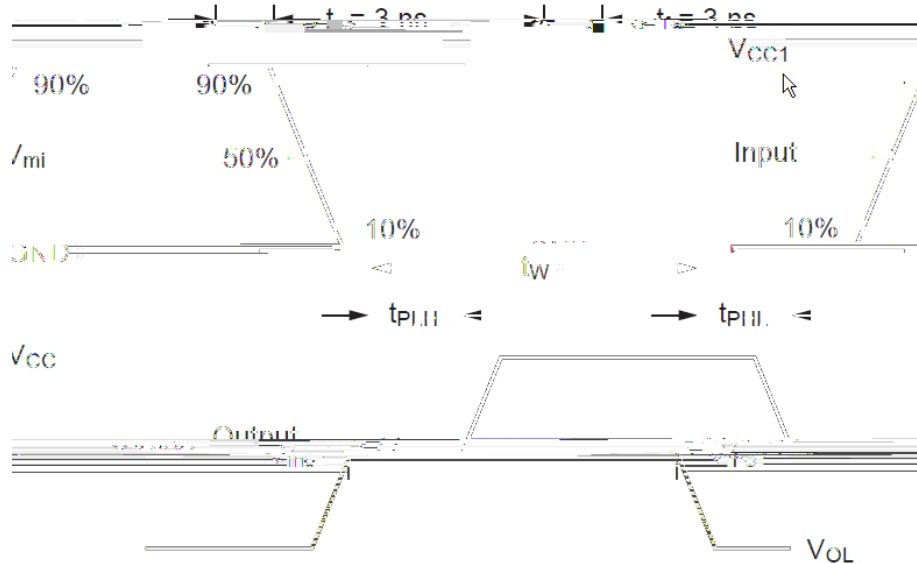


Figure 4. Waveform Timing and Non-Inverting Function

Table 1. AC LOAD TABLE

Symbol	V_{CC}					
	3.3 V \pm 0.3 V	2.5 V \pm 0.2 V	1.8 V \pm 0.15 V	1.5 V \pm 0.10 V	1.2 V \pm 0.10 V	1.0 V
V_{mi}	1.5V	$V_{CC1}/2$	$V_{CC1}/2$	$V_{CC1}/2$	$V_{CC1}/2$	$V_{CC1}/2$
V_{mo}	1.5V	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$

FXLP34

ORDERING INFORMATION

Part Number	Top Mark	Package Type	Shipping†
FXLP34P5X	X34	5-Lead SC70, EIAJ SC-88a, 1.25 mm Wide (Pb-Free)	3000 / Tape & Reel
FXLP34L6X	X3	SIP6, 6-Lead MicroPak, 1.00 mm Wide (Pb-Free)	5000 / Tape & Reel
FXLP34FHX	X3	UDFN6, 6-Lead, MicroPak2, 1x1 mm Body, .35 mm Pitch (Pb-Free)	5000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

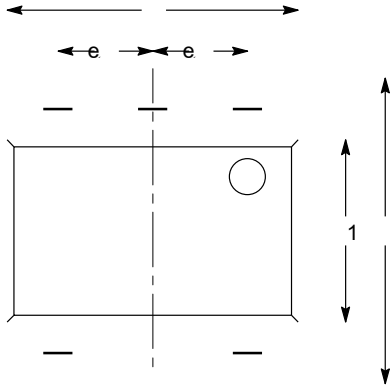
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SIP6 1.45X1.0

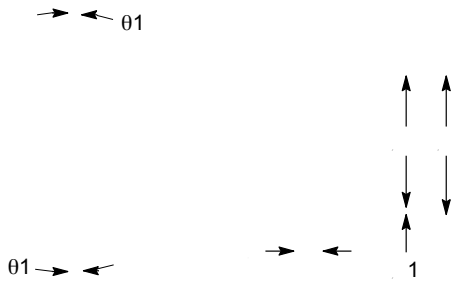
2. DIM



SC 88A (SC 70 5 Lead), 1.25x2



TOP VIEW



SIDE VIEW



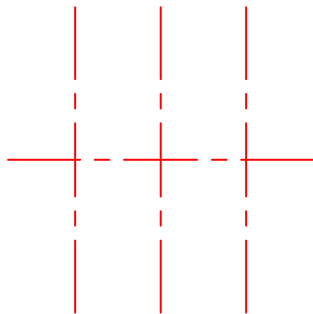
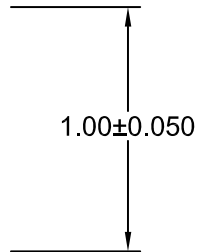
END VIEW

Notes:

- (1) All dimensions are in millimeters unless otherwise specified.
- (2) All dimensions are in inches unless otherwise specified.

UDFN6 1.0X1.0, 0.35P
CASE 517DP
ISSUE O

DATE 31 AUG 2016



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